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C. J. J. J.
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Osterheld et al.
Serial No. : 10/040,108
Filed : October 29, 2001
Title : POLISHING PAD HAVING A GROOVED PATTERN FOR USE IN
CHEMICAL MECHANICAL POLISHING

Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Prior to examination, please amend the application as follows:

In the claims:

Add claims 55-62.

1355. A polishing pad for polishing a substrate in a chemical mechanical polishing system, comprising:

a polishing surface having a plurality of grooves, the grooves having a depth of 0.03 inches, a width of 0.02 inches, and a pitch between about 0.09 and 0.24 inches.

1456. The polishing pad of claim 1355, wherein the grooves are uniformly spaced over the polishing surface.

1557. The polishing pad of claim 1355, wherein the grooves have a pitch of 0.12 inches.

1658. The polishing pad of claim 1355, wherein the polishing pad further comprises an upper layer and a lower layer, the grooves being formed in the upper layer.

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

Date of Deposit April 29, 2002

Signature Carlos J. J. J.

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